

HIGH-RELIABILITY SOLDERS FOR THERMAL APPLICATIONS



- Optimizes the burn-in process
- Improves process yield
- Decreases testing costs
- Easy to handle
- Resists bake-out or pump-out
- Can be used for multiple insertions
- Applies easily with a vacuum nozzle or tweezers
- Packaged to your requirements in trays or tape & reel



Heat-Spring® Preforms

- Patterned to optimize contact with non-planar surfaces 86W/mK
- Provides uniform contact between the burn-in head and the chip
- Increases thermal conductivity
- Cleans with no residue
- Recyclable and reclaimable



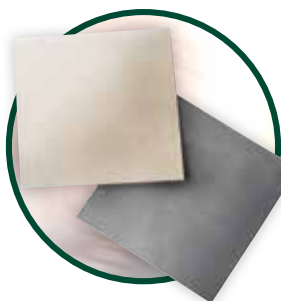
Heat-Spring® HSK

- Recommended specifically for burn-in applications where multiple insertions are required
- Provides uniform contact with low resistance for high-density heat loads
- Typically clad with a thin diffusion barrier, which serves as the contact surface for burn-in and test applications
- No staining or cracking
- Can be made with or without aluminum cladding
- Recommended minimum thickness: 10mil (250 μ m)
- Recyclable and reclaimable for credit



Heat-Spring® HSD

- Designed for interfaces with tight surface control >30psi
- Recommended for small, well-designed interfaces with flat, smooth, and parallel surfaces (greater than 2mil non-planar)
- Recommended minimum thickness: 4mil (100 μ m)
- Maximum thickness: 12mil (300 μ m)



HSMF-OS Preforms

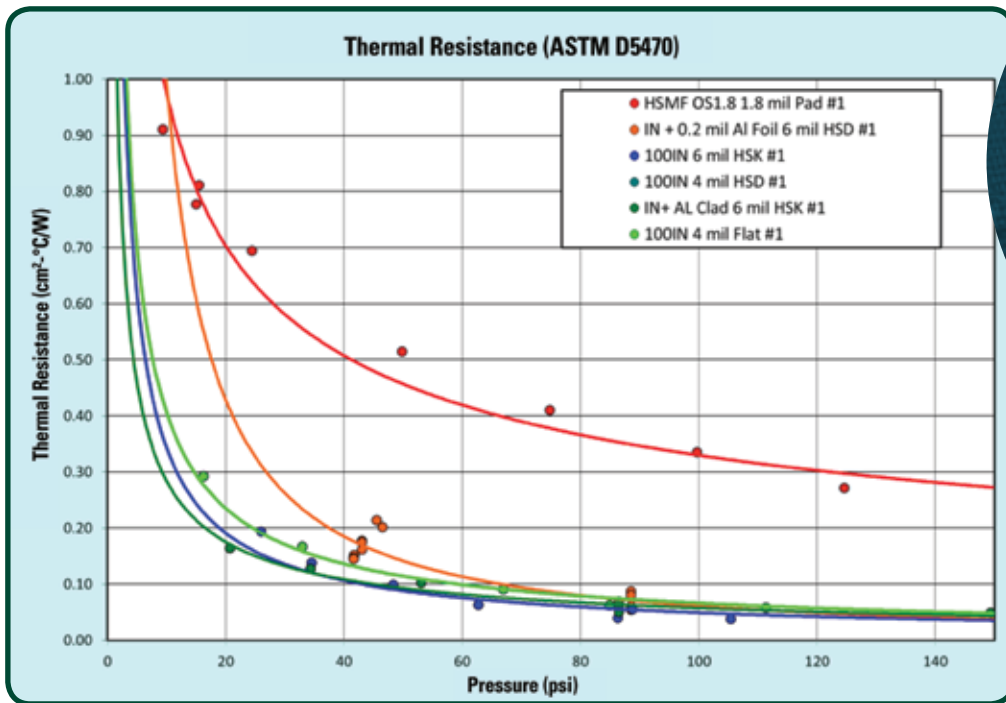
- Tacky for easy placement
- Compliant and compressible
- Durable

From One Engineer To Another®



THERMAL APPLICATIONS

Under pressure, Indium Corporation Thermal Interface Materials show very low thermal resistance.



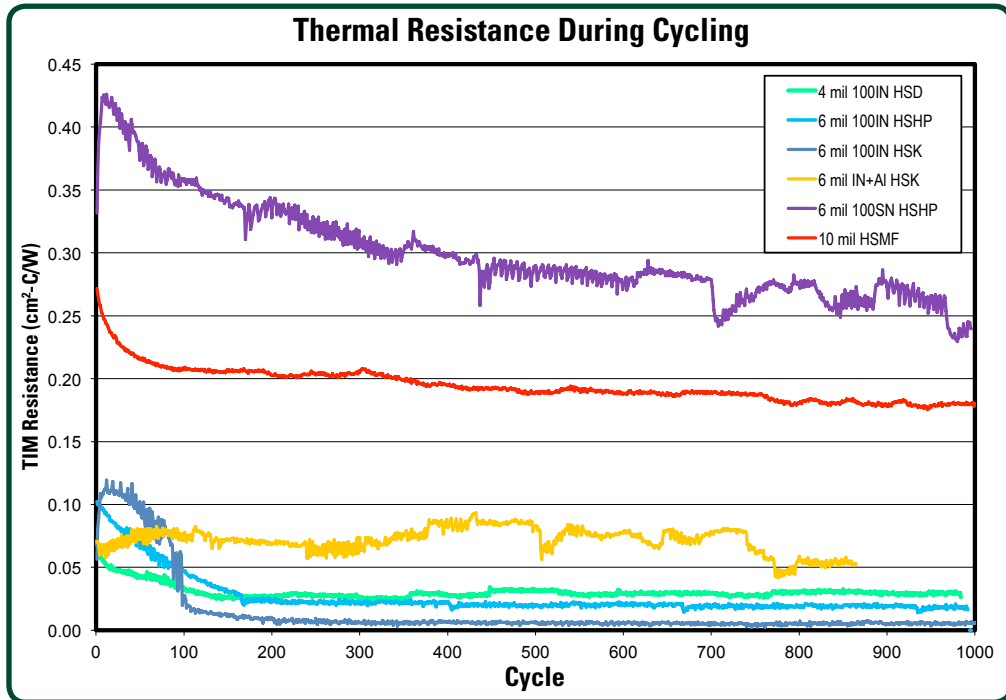
Heat-Spring® preforms are available in several metals, but the most popular are:

Indalloy® 4 – 99.99In

Indalloy® 3 – 90In/10Ag

Indalloy® 1E – 52In/48Sn

Indalloy® 290 – 97In/3Ag



Contact our expert today: shomer@indium.com

Learn more: www.indium.com/TIMs

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